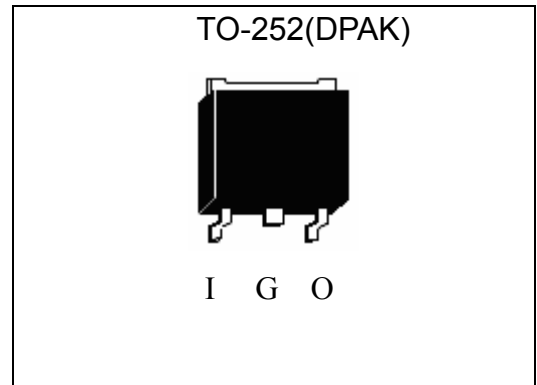


Three Terminal Positive Voltage Regulators

LM7805BJ3



Description

The LM7805BJ3 series of fixed voltage monolithic integrated circuit voltage regulators is designed for a wide range of applications. These applications include on-card regulation for elimination of noise and distribution problems associated with single point regulation. Each of these regulators can deliver up to 1A of output current. The internal current limiting and thermal shutdown features of these regulators make them essentially immune to overload.

Features:

- Internal Short-Circuit Current Limiting
- High Power Dissipation Capability
- Internal Thermal Overload Protection
- No External Components Required
- Output Transistor Safe Area Compensation
- Pb-free lead plating

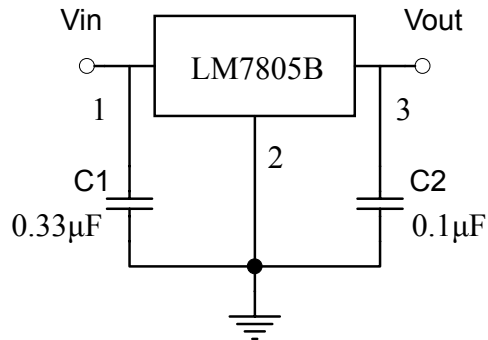
Absolute Maximum Ratings (Ta=25°C)

Parameter	Ratings	Unit
Input Voltage	35	V
Output Current	1	A
Operating Junction Temperature Range	-40 ~ +125	°C
Storage Temperature Range	-55 ~ +125	°C
Thermal Resistance, Junction to Ambient (R _{θJA})	125	°C/W
Thermal Resistance, Junction to Case (R _{θJC})	12.5	°C/W

Ordering Information

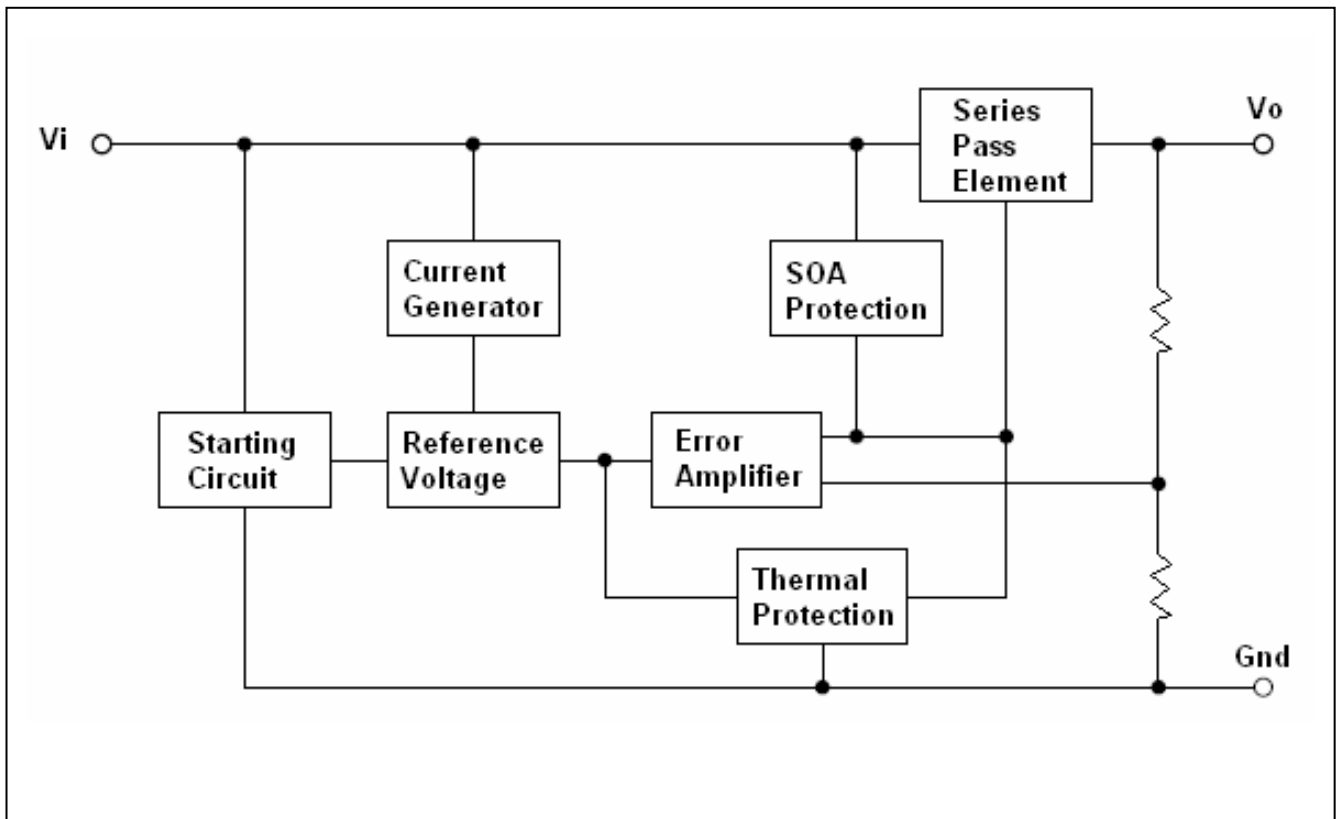
Device	Output Voltage Tolerance	Package	Shipping	Marking
LM7805BJ3	±5%	TO-252 (Pb-free lead plating)	2500 pcs / Tape & Reel	7805

Typical Application Circuit



Note:
 C1 and C2 are required if regulator is located far from power supply filter and load, or oscillation may induced on the loop.

Block Diagram

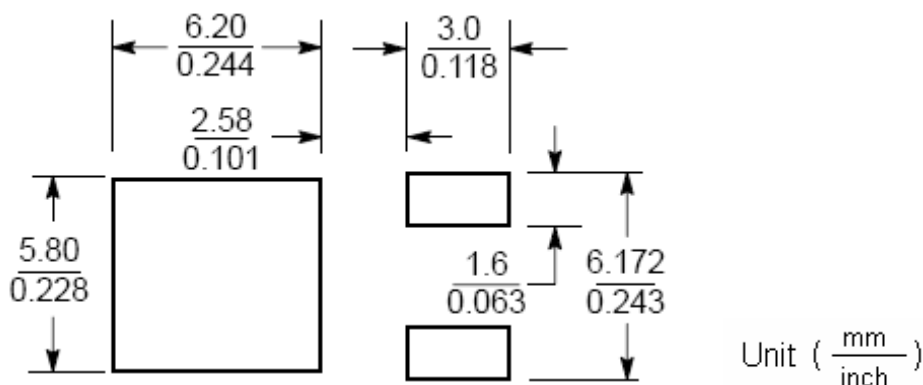


Electrical Characteristics

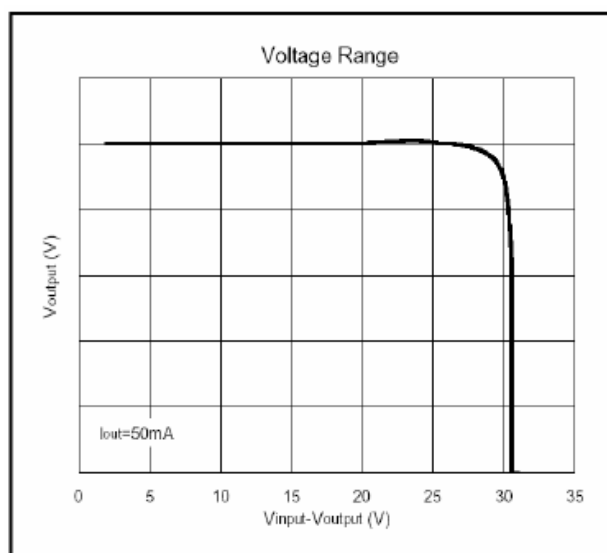
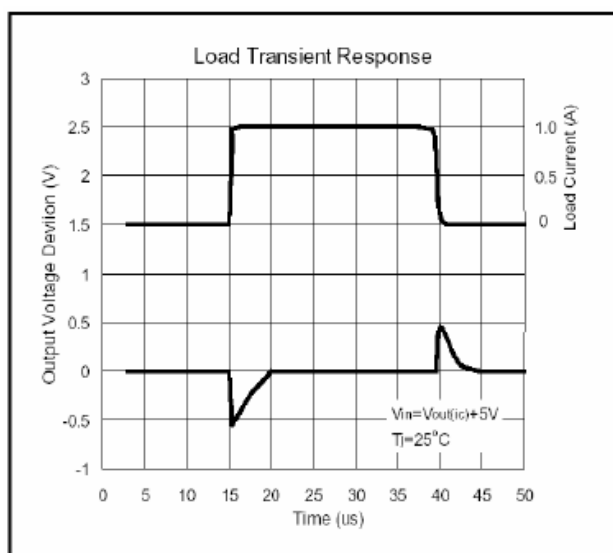
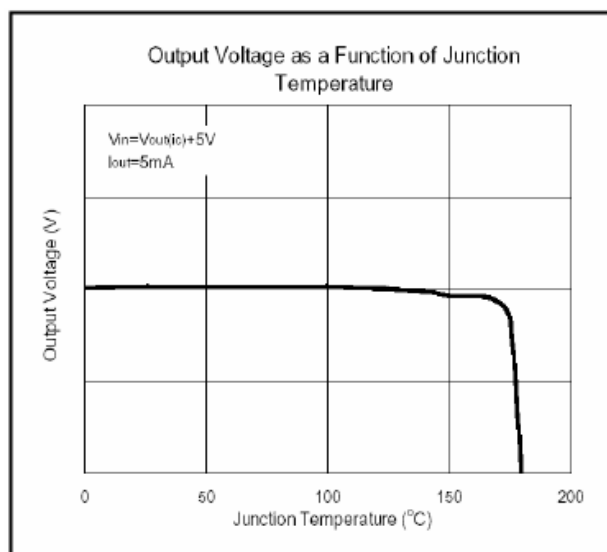
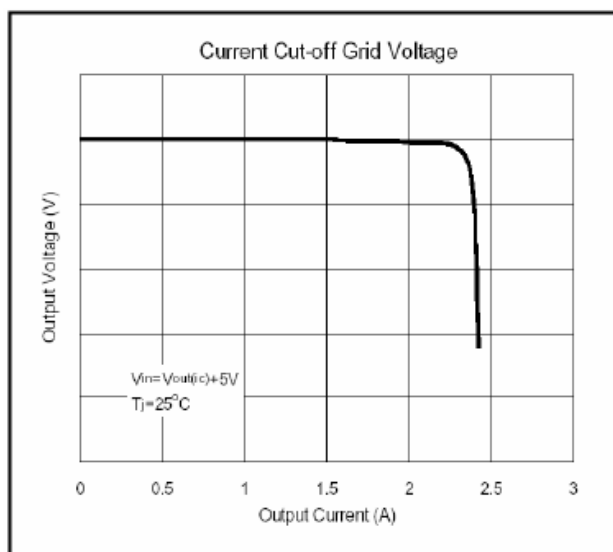
(Tj=0~125°C, Vin=10V, Io=500mA, Cin=0.33uF, Cout=0.1uF, unless otherwise noted)

Symbol	Parameter	Min	Typ	Max	Conditions	Units
V _O	Output Voltage	4.75	-	5.25	Vin=10V, Io=500mA, Tj=25°C 7.5V≤Vin≤20V, 5mA≤Io≤1A, PD≤15W	V
ΔV _O	Line Regulation	-	3	50	7V≤Vin≤25V, Tj=25°C	mV
		-	1	25	8V≤Vin≤12V, Tj=25°C	
ΔV _O	Load Regulation	-	-	100	5mA≤Io≤1A, Tj=25°C	mV
		-	-	50	250mA≤Io≤750mA, Tj=25°C	
I _Q	Quiescent Current	-	-	8	Vin=10V, Io=500mA, Tj=25°C	mA
ΔI _Q	Quiescent Current Change	-	-	0.5	5mA≤Io≤1A	mA
		-	-	1.3	7V≤Vin≤25V	
V _n	Output Noise Voltage	-	40	-	10Hz≤f≤100KHz, Tj=25°C	μV
RR	Ripple Rejection	-	80	-	8V≤Vin≤18V, f=120Hz, Tj=25°C	dB
VD	Dropout Voltage	-	2	-	Io=1A, Tj=25°C	V
ISC	Output Short Circuit Current	-	250	-	Vin=35V, Tj=25°C	mA
IPK	Peak Output Current	-	1.8	-	Tj=25°C	A
ΔV _O /ΔT _j	Temperature Stability	-	-0.6	-	Io=5mA, 0°C≤Tj≤125°C	mV/°C

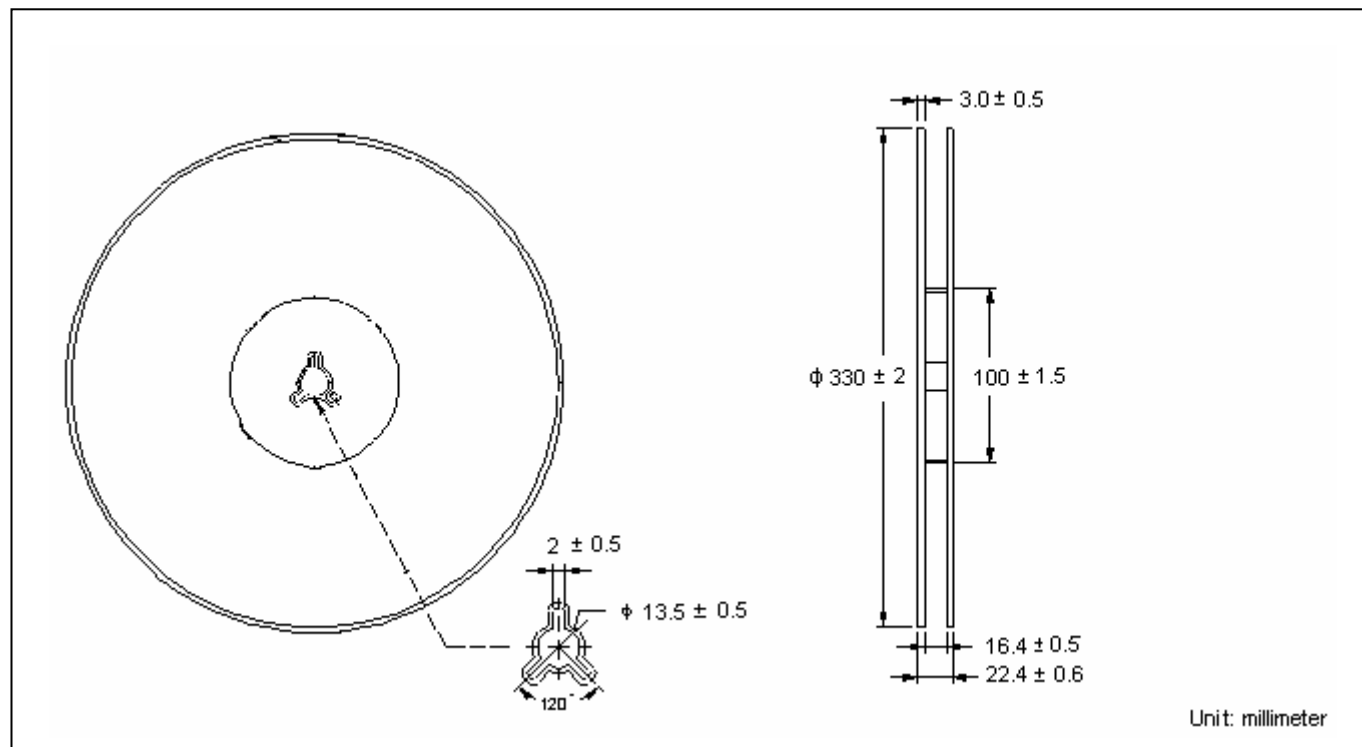
Recommended soldering footprint



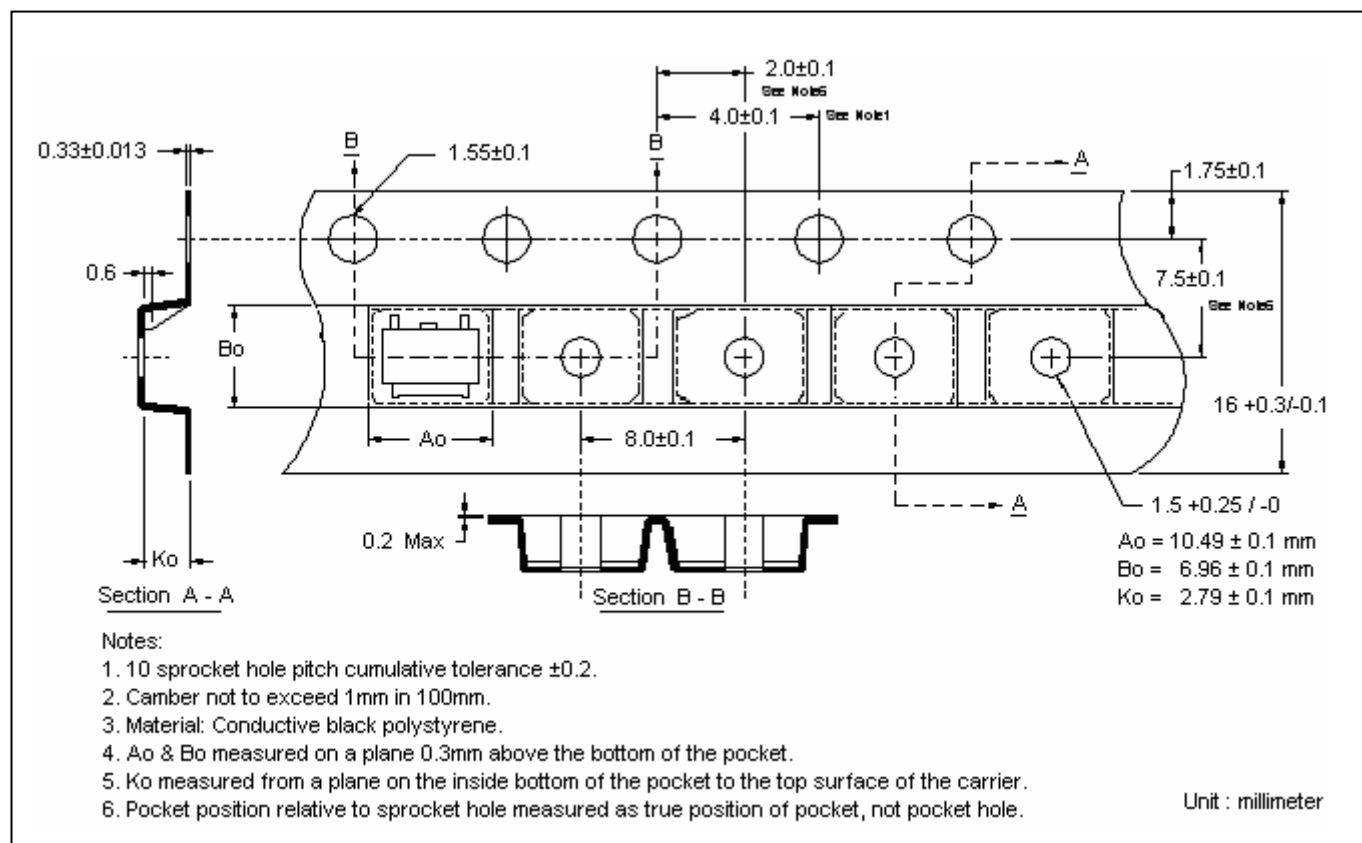
Characteristic Curves



Reel Dimension



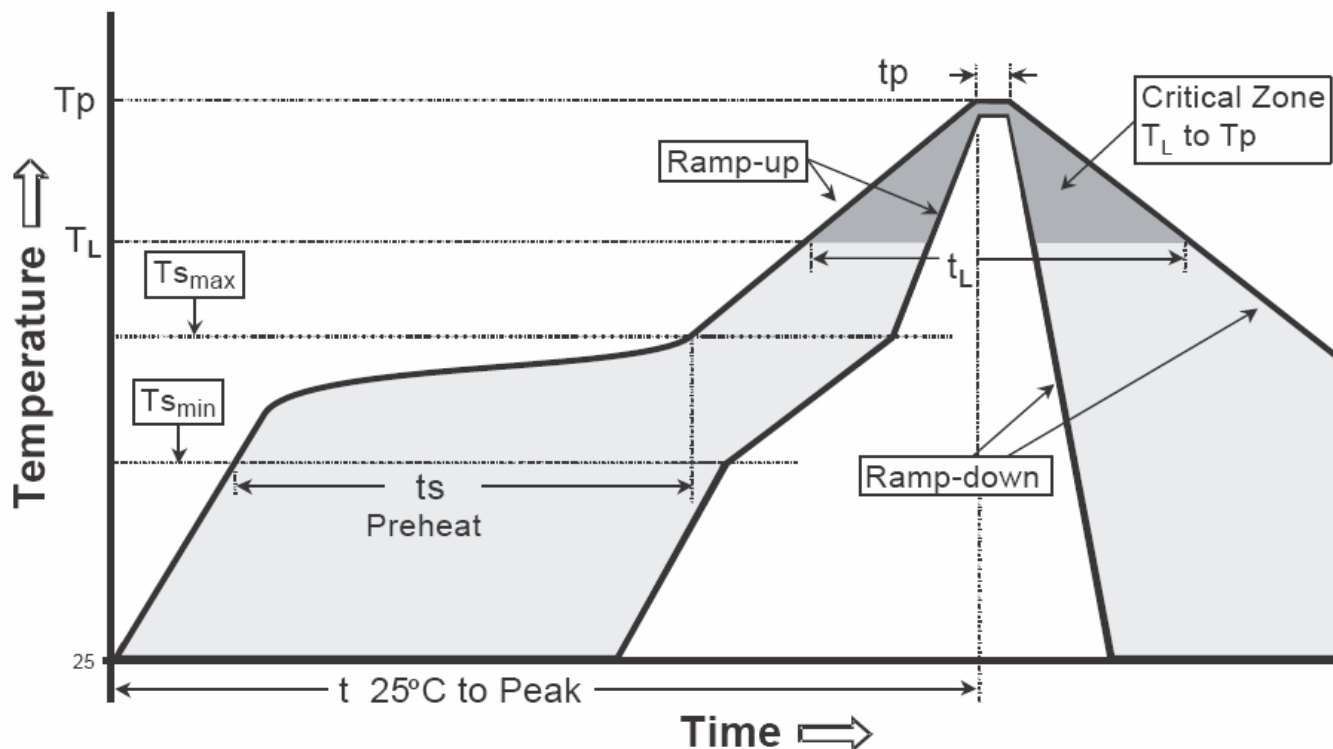
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

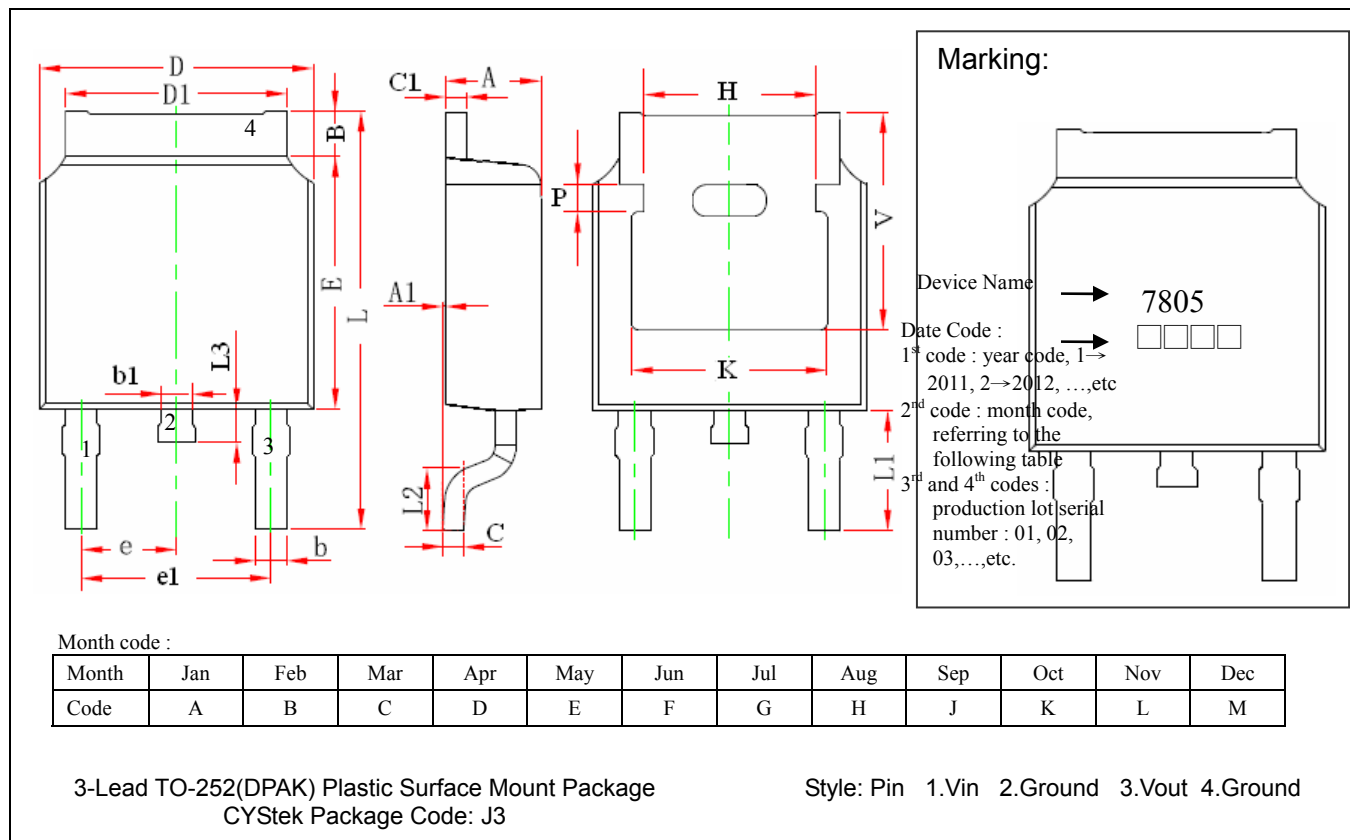
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(Ts min)	100°C	150°C
-Temperature Max(Ts max)	150°C	200°C
-Time(ts min to ts max)	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (Tl)	183°C	217°C
- Time (tL)	60-150 seconds	60-150 seconds
Peak Temperature(Tp)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

TO-252(DPAK) Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.087	0.094	2.200	2.400	e	0.086	0.094	2.186	2.386
A1	0.000	0.005	0.000	0.127	e1	0.172	0.188	4.372	4.772
B	0.039	0.048	0.990	1.210	H	0.163	REF	4.140	REF
b	0.026	0.034	0.660	0.860	K	0.190	REF	4.830	REF
b1	0.026	0.034	0.660	0.860	L	0.386	0.409	9.800	10.400
C	0.018	0.023	0.460	0.580	L1	0.114	REF	2.900	REF
C1	0.018	0.023	0.460	0.580	L2	0.055	0.067	1.400	1.700
D	0.256	0.264	6.500	6.700	L3	0.024	0.039	0.600	1.000
D1	0.201	0.215	5.100	5.460	P	0.026	REF	0.650	REF
E	0.236	0.244	6.000	6.200	V	0.211	REF	5.350	REF

Notes: 1.Controlling dimension: millimeters.

2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead : Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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